

1 Description

The C236S-HT series is a miniature 1-Form A solid state relay in a 4-pin SOP package that employs optically coupled MOSFET technology to provide 1500V of input to output isolation. The optically coupled input is controlled by a highly efficient GaALAs infrared LED and MOSFETs on the output side.

Operating Temperature: -40 ~ +105 350mA Max.

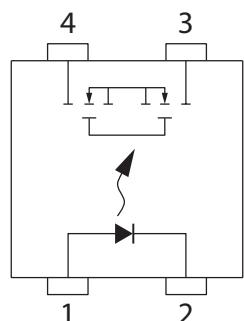
Device Information

Part Series	Package	Body Size (mm)
C236S-HT	SOP	4.4 x 4.3 x 2.0

Device Package



4 Schematic



- 1. LED Anode
- 2. LED Cathode
- 3, 4. Drain (MOS FET)

2 Features

- SOP package 4 Pin type in miniature design (4.4 x 4.3 x 2.0 mm / .173 x .169 x .083 inches)
- Low driver power requirements (TTL/CMOS Compatible)
- No moving parts
- High reliability
- Arc-Free with no snubbing circuits
- 1500 Vrms Input/Output isolation
- UL No. FPQU2.E351594 approved
- Tape & Reel version approved

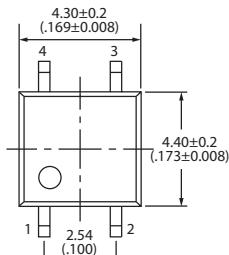
3 Applications

- Telecommunications (PC, electronic notepad)
- Measuring and Testing equipment
- Industrial control
- Security equipment
- High speed inspection machines

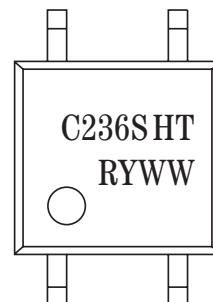
5 Device Package Details

5.1 Outside Dimensions

Millimeters (Inches)



5.2 Device Marking

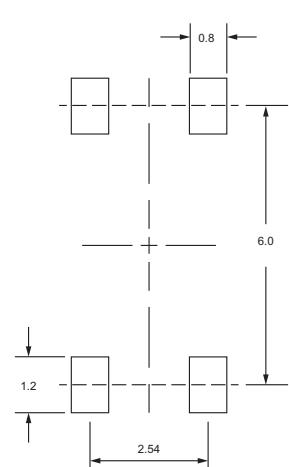
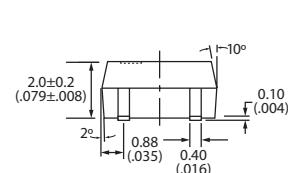


Notes:

YWW = Y: Year code / W: Week code

5.3 Recommended Mounting Pad

Units: Millimeters / Tolerance: ±0.1



6 Specifications

6.1 Absolute Maximum Ratings

Parameters	Symbol	Rating	Unit
Input	Continuous LED Current	I _F	50 mA
	Peak LED Current (f=100 Hz, duty=1%)	I _{FP}	1000 mA
	LED Reverse Voltage	V _R	5 V
	Input Power Dissipation	P _{In}	75 mW
Output	Load Voltage	V _L	60 V (AC peak or DC)
	Load Current	I _L	350 mA
	Peak Load Current (100 ms; 1 pulse)	I _{Peak}	4.0 A
	Output Power Dissipation	P _{out}	350 mW
Total Power Dissipation	P _T	400 mW	
I/O Breakdown Voltage (RH=60%, 1 min)	V _{I/O}	1500 Vrms	
Operating Temperature	T _{opr}	-40 to +105 °C	
Storage Temperature	T _{stg}	-40 to +105 °C	
Pin Soldering Temperature (10 sec. max)	T _{sol}	260 °C	

6.2 Electro-Optical Characteristics

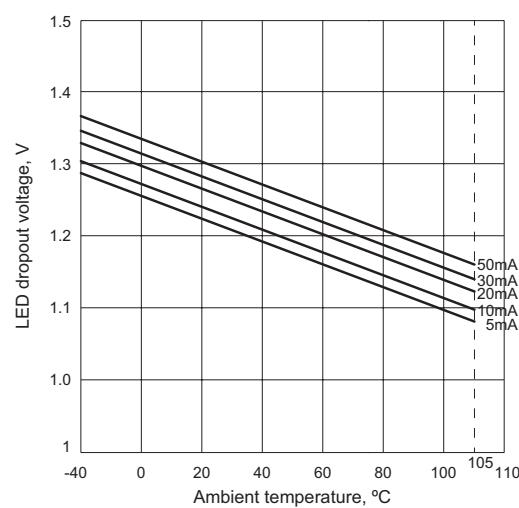
Parameters	Symbol	Conditions	Min.	Typ.	Max.	Unit
Input	LED Forward Voltage	V _F	I _F =10mA	1.2	1.4	V
	Operation LED Current	I _{FON}		0.5	2.0	mA
	Recovery LED Current	I _{F OFF}		0.35	0.5	mA
	Recovery LED Current	V _{F OFF}		0.7		V
Output	On-Resistance	R _{on}	I _F =5mA, I _L =100mA Time to flow is within 1 sec.	0.13	0.5	Ω
	Off-State Leakage Current	I _{LEAK}	V _L =Rating		1.0	μA
	Output Capacitance	C _{out}			115	pF
Trans- mission	Turn-On Time	T _{ON}	I _F =5mA, I _L =100mA	1.0	1.3	ms
	Turn-Off Time	T _{OFF}		0.6	0.8	ms
Coupled	I/O Isolation Resistance	R _{I/O}	DC500V	10 ¹⁰		Ω
	I/O Capacitance	C _{I/O}	f=1MHz	0.8	1.5	pF

Notes:

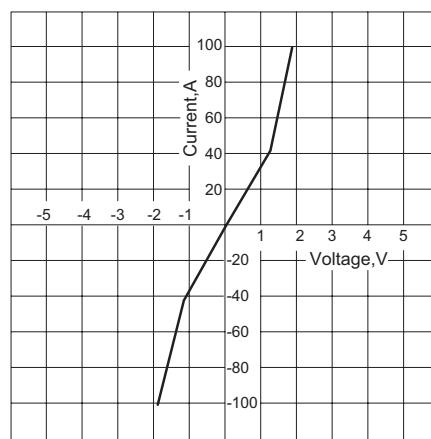
Ta=25°C

7 C208S Series Graphs

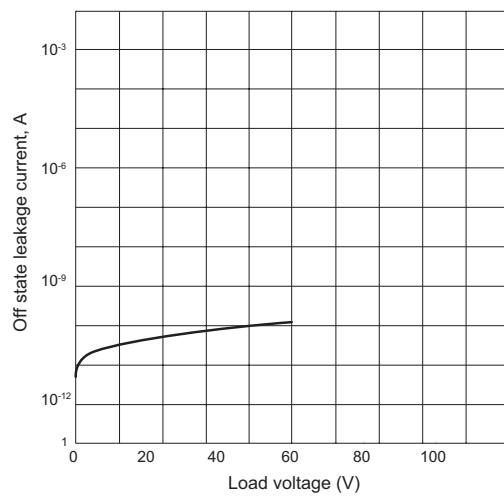
LED Forward Voltage Vs. Ambient Temperature



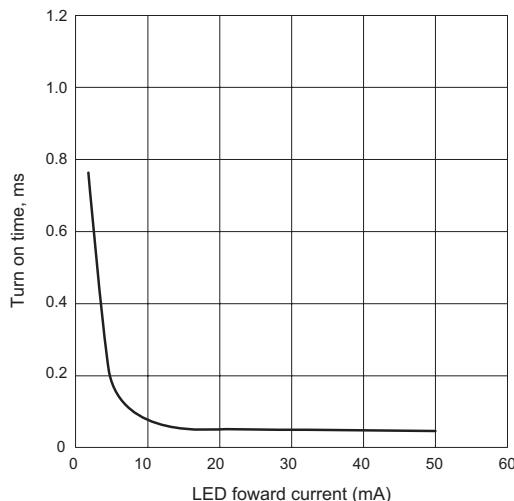
**Voltage Vs. Current Characteristics
of Output at MOSFET Portion**



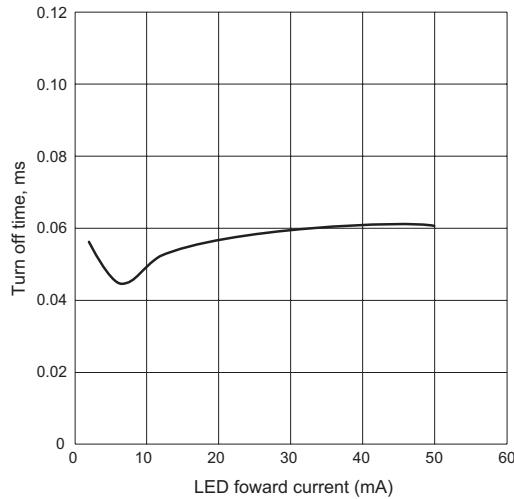
Off-State Leakage Current Vs. Load Voltage



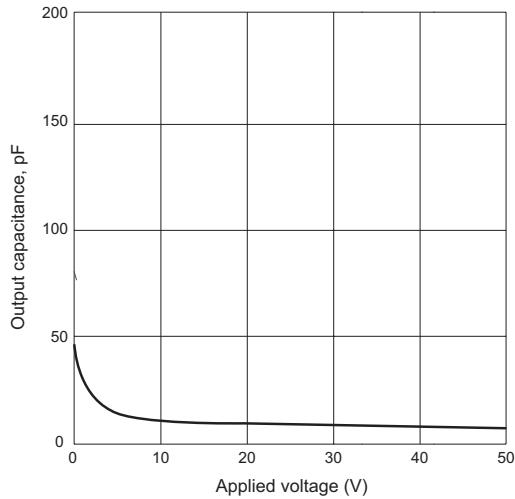
LED Forward Current Vs. Turn-On Time Characteristics



LED Forward Current Vs. Turn-Off Time Characteristics

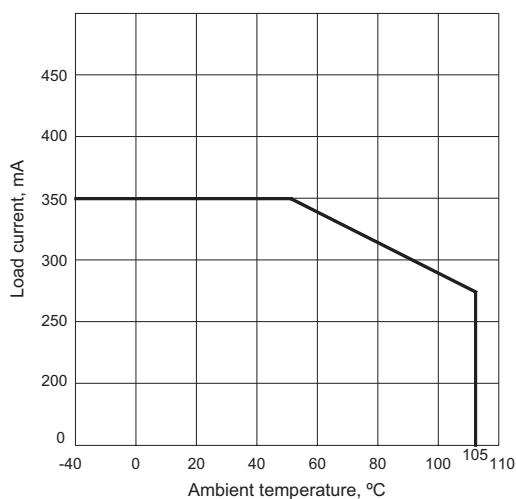


Applied Voltage Vs. Output Capacitance Characteristics

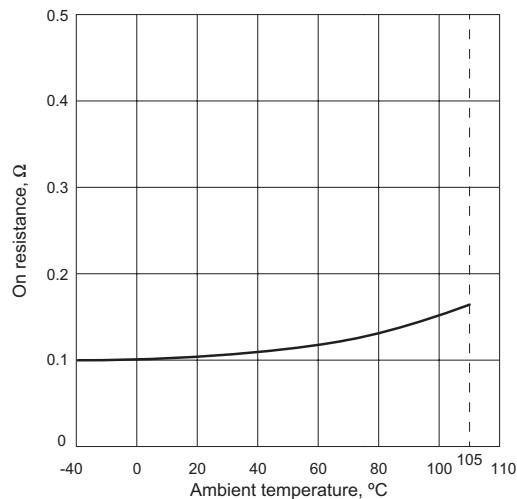


7 C236S-HT Series Graphs

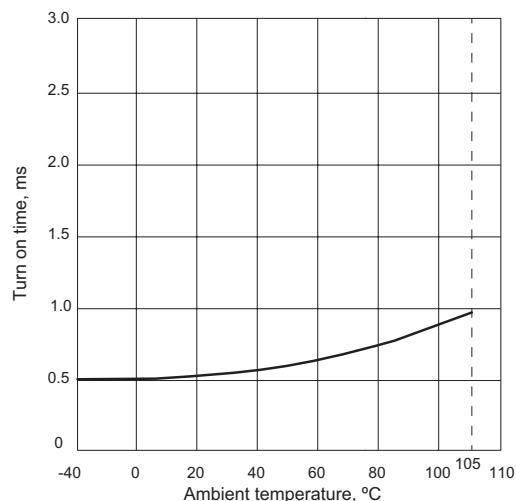
Load Current Vs. Ambient Temperature



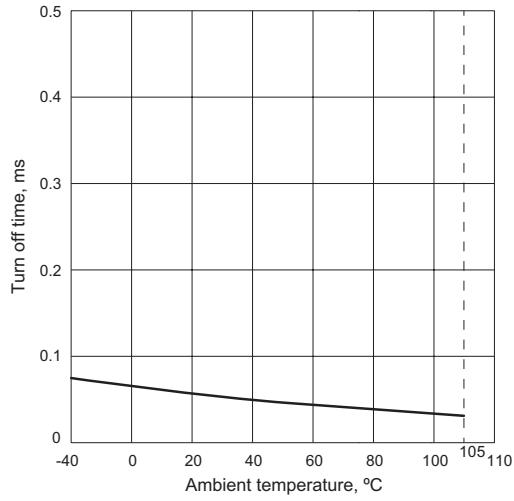
On-Resistance Vs. Ambient Temperature



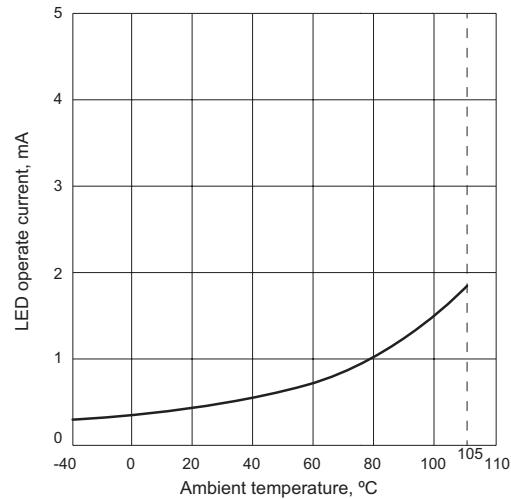
Turn-On Time Vs. Ambient Temperature



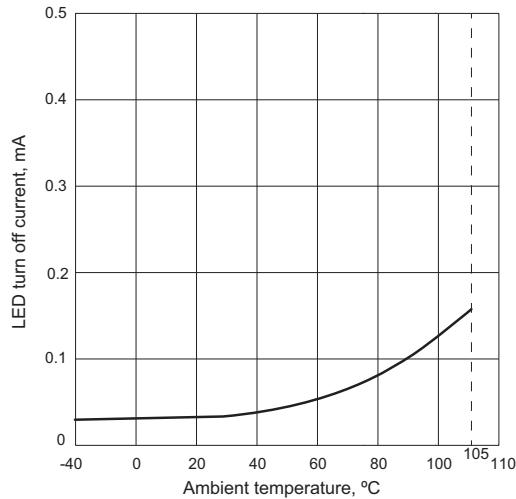
Turn-Off Time Vs. Ambient Temperature



LED Operate Current Vs. Ambient Temperature



LED Turn-Off Current Vs. Ambient Temperature



8 Recommended Soldering Conditions

Infrared Reflow Soldering

- ▶ Peak reflow soldering: 260°C or below (package surface temperature)
- ▶ Time of peak reflow temperature: 10 seconds
- ▶ Time of temperature higher than 230°C: 30-60 seconds
- ▶ Time to preheat temperature from 180~190°C: 60-120 seconds
- ▶ Number of reflows: Two
- ▶ Flux: Rosin flux containing small amount of chlorine
(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)